

LINEAR TECHNOLOGY MATERIALS DECLARATION

LT1584CT-3.45#PBF		(Engineering Calculation)		TO-220				
(printed on: 7/16/2011 12:41:24 PM)				TOTAL MASS (g):		1.899045		
COMPONENT	VENDOR/	CONSTITUENT	CAS	CONSTITUENT	CONSTITUENT	CONSTITUENT		
MATERIAL	INDUSTRY NAMES	NAME	NUMBER	MASS (g)	(PPM) OF MATERIAL	(PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.00668	1000000	3517.558		
Die Coat	Dow Corning	Silicone	67762-90-7	0	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	1.327316	998500	698938.8		
		Iron (Fe)	7439-89-6	0	0	0		
		Phosphorus (P)	7723-14-0	0	0	0		
		Zinc (Zn)	7440-66-6	0	0	0		
		Nickel (Ni)	7440-02-0	0	0	0		
		Silicon (Si)	7440-21-3	0	0	0		
		Magnesium (Mg)	7439-95-4	0	0	0		
		Tin (Sn)	7440-31-5	0.001994	1500	1050.002		
		Lead Frame Total:				1.331304	1000000	701038.7
Plating	PMI	Exter. Plating Pb	7439-92-1	0	0	0		
		Exter. Plating Sn	7440-31-5	0.01064091	1000000	5603.295		
		External Plating Total:				0.01064091	1000000	5603.295
		Inter. Plating Ni	7440-02-0	0.009	826446.3	4739.225		
		Inter. Plating Ag	7440-22-4	0.00189	173553.7	995.2371		
		Internal Plating Total:				0.01089	1000000	5734.461
Die Attach	95Pb / 5 Sn	Silver (Ag)	7440-22-4	0	0	0		
		Tin (Sn)	7440-31-5	0.000141	50000	74.24785		
		Lead (Pb)	7439-92-1	0.002671	950000	1406.496		
		Silica (SiO2)	60676-86-0	0	0	0		
		Metal Oxide		0	0	0		
		Antimony (Sb)	7440-36-0	0	0	0		
		Resin (EP)		0	0	0		
Die Attach Total:				0.002812	1000000	1480.744		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.055248	103000	29092.52		
		Bromine (Br)	40039-93-8	0	0	0		
		Silica (SiO2)	60676-86-0	0.480069	895000	252795		
		Antimony	1309-64-4	0	0	0		
		Trioxide (Sb2O3)						
		Metal Hydroxid		0	0	0		
		Carbon Black (C)	1333-86-4	0.001073	2000	565.0209		
Encapsulation Total:				0.53639	1000000	282452.5		
Bond Wire	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000328	1000000	172.7184		
Estimated								
				TOTAL MASS (g):		1.899045		